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Advances In Chemical Mechanical Planarization

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Advances in Chemical Mechanical Planarization (CMP) - 1st ...

The primary aim of this issue of MRS Bulletin is to present an overview of the materials issues in chemical-mechanical planarization (CMP), also known as chemical-mechanical polishing, a process that is used in the semiconductor industry to isolate and connect individual transistors on a chip. The CMP process has been the fastest-growing semiconductor operation in the last decade, and its future growth is being fueled by the introduction of copper-based interconnects in advanced ...

Advances in Chemical-Mechanical Planarization | MRS ...

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Therefore, chemical—mechanical planarization (CMP) is a key process in the final definition of the inlaid copper wires on a circuit. A second advance in the back-end processing of copper is the changing of the dielectric from SiO₂ to a Low-k material, which allows a thicker layer of dielectric to be used.

MRS Bulletin: Volume 27 - Advances in Chemical-Mechanical ...

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Taesung Kim. A retainer ring structure was investigated to improve non-uniformity in a chemical mechanical planarization (CMP) process. During the CMP process, the stress distribution on the wafer...

Advances in Chemical-Mechanical Planarization | Request PDF

Chemical Mechanical Planarization Chemical mechanical polishing (CMP) is a powerful fabrication technique that uses chemical oxidation and mechanical abrasion to remove material and achieve very high levels of planarity. From: Handbook of Thin Film Deposition (Third Edition), 2012

Chemical Mechanical Planarization - an overview ...

The effects of consumables on material removal and scratch propensity in Chemical Mechanical Planarization. Chapter 5 in Recent Advances in Abrasives Research (Bähre, Dirk, editor), Nova Science ...

Kuan-Chuen Wu - Data Science Fellow - Insight Data Science ...

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A scanning mobility particle sizer (SMPS) was used for measuring the size of a sub-10 nm chemical mechanical planarization slurry abrasive. An atomizer and an electrospray were used for aerosolizat...

Application of electrospray-scanning mobility particle ...

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Chemical mechanical polishing or planarization is a process of smoothing surfaces with the combination of chemical and mechanical forces. It can be thought of as a hybrid of chemical etching and free abrasive polishing. Usage in semiconductor fabrication

Chemical-mechanical polishing - Wikipedia

Yunhui Zhu's 41 research works with 146 citations and 2,128 reads, including: Fabrication and Comparison of Bumpless Wafer-on-Wafer Integration and Bump-Containing Chip-on-Chip Integration

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